



Reliability Data Report

Product Family R526

LTC3103 \ LTC3104 \ LTC3111 \ LTC3112 \ LTC3114 \ LTC3115 \
LTC3118 \ LTC3121 \ LTC3122 \ LTC3124 \ LTC3129 \ LTC3245 \
LTC3255 \ LTC3260 \ LTC3261 \ LTC3265 \ LTC3355 \ LTC3388 \
LTC3582 \ LTC3600 \ LTC3602 \ LTC3603 \ LTC3618 \ LTC3630 \
LTC3631 \ LTC3632 \ LTC3637 \ LTC3638 \ LTC3639 \ LTC3640 \
LTC3641 \ LTC3642 \ LTC3646 \ LTC3647 \ LTC3649 \ LTC3676 \
LTC3769 \ LTC3774 \ LTC3775 \ LTC3784 \ LTC3786 \ LTC3787 \
LTC3788 \ LTC3789 \ LTC3790 \ LTC3807 \ LTC3829 \ LTC3833 \
LTC3838 \ LTC3839 \ LTC3850 \ LTC3851 \ LTC3852 \ LTC3853 \
LTC3854 \ LTC3855 \ LTC3856 \ LTC3857 \ LTC3858 \ LTC3859 \
LTC3862 \ LTC3863 \ LTC3864 \ LTC3865 \ LTC3866 \ LTC3867 \
LTC3868 \ LTC3869 \ LTC3870 \ LTC3874 \ LTC3875 \ LTC3876 \
LTC3877 \ LTC3878 \ LTC3879 \ LTC3880 \ LTC3882 \ LTC3883 \
LTC3884 \ LTC3886 \ LTC3887 \ LTC3890 \ LTC3891 \ LTC3892 \
LTC3899 \ LTC7149

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Report generated on: Mon Aug 29 10:42:30 PDT 2016

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2, 3}
SSOP/TSSOP	8372	0645	1450	4363	0
SOIC/MSOP	1540	0816	1510	3484	0
QFN/DFN	8175	0816	1515	6885	0
Totals	18,087	-	-	14,732	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) ⁴	No. of FAILURES
SSOP/TSSOP	10647	0911	1526	22675	0
SOIC/MSOP	1215	1040	1510	3148	0
QFN/DFN	1714	1043	1544	4704	0
Totals	13,576	-	-	30,527	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SSOP/TSSOP	44581	0652	1521	1598	0
SOIC/MSOP	13678	0908	1521	1560	0
QFN/DFN	39388	0649	1531	1644	0
QFP	77	1311	1311	12	0
Totals	97,724	-	-	4,814	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SSOP/TSSOP	43691	0652	1536	6900	0
SOIC/MSOP	13584	0908	1521	6069	0
QFN/DFN	43115	0639	1544	8310	0
Totals	100,390	-	-	21,279	0

TEMP CYCLE FROM -40 TO 125 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	150	1406	1406	151	0
Totals	150	-	-	151	0

- (1) Assumes Activation Energy = 0.7 Electron Volts
 (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level = 0.8 FITS
 (3) Mean Time Between Failure in Years = 141929.84
 (4) Assumes 20X Acceleration from 85 °C to +130 °C

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SSOP/TSSOP	45201	0652	1536	6725	0
SOIC/MSOP	12263	0908	1521	4939	0
QFN/DFN	39441	0652	1544	7632	0
Totals	96,905	-	-	19,296	0
HIGH TEMPERATURE BAKE AT 125 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	148	1413	1430	148	0
Totals	148	-	-	148	0
HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	4433	0726	1531	2222	0
SSOP/TSSOP	1358	0812	1517	1243	0
SOIC/MSOP	2404	0908	1510	2359	0
Totals	8,195	-	-	5,824	0
HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	3350	0726	1521	3154	0
SSOP/TSSOP	690	0812	1018	653	0
SOIC/MSOP	834	0905	1336	1052	0
Totals	4,874	-	-	4,859	0